



US00D420022S

# United States Patent [19]

[11] Patent Number: **Des. 420,022**

**Burkhart et al.**

[45] Date of Patent: **\*\* Feb. 1, 2000**

[54] **ELECTROSTATIC CHUCK WITH IMPROVED SPACING AND CHARGE MIGRATION REDUCTION MASK**

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[57] **CLAIM**

The ornamental design for an electrostatic chuck with improved spacing and charge migration reduction mask, as shown and described.

[73] Assignee: **Applied Materials, Inc.**, Santa Clara, Calif.

**DESCRIPTION**

[\*\*] Term: **14 Years**

[21] Appl. No.: **29/081,238**

FIG. 1 is a top view of the electrostatic chuck having the improved spacing and charge migration reduction mask;

[22] Filed: **Dec. 24, 1997**

FIG. 2 is an elevation view when looking to the right along the x-axis in FIG. 1, the view when looking to the left along the x-axis in FIG. 1 being identical to that of FIG. 2 thereof;

**Related U.S. Application Data**

[63] Continuation-in-part of application No. 08/639,841, May 8, 1996, Pat. No. 5,764,471.

FIG. 3 is a detailed view of part of the surface seen in FIG. 2 thereof;

[51] **LOC (7) Cl.** ..... **15-09**

FIG. 4 is a bottom view thereof;

[52] **U.S. Cl.** ..... **D15/140**

FIG. 5 is an elevation view when looking down along the y-axis in FIG. 1 thereof; and,

[58] **Field of Search** ..... D15/140; 361/234, 361/235; 279/128; 269/8, 903

FIG. 6 is an elevation view when looking up along the y-axis in FIG. 1 thereof.

[56] **References Cited**

**U.S. PATENT DOCUMENTS**

5,528,451 6/1996 Su ..... 279/128

**1 Claim, 2 Drawing Sheets**

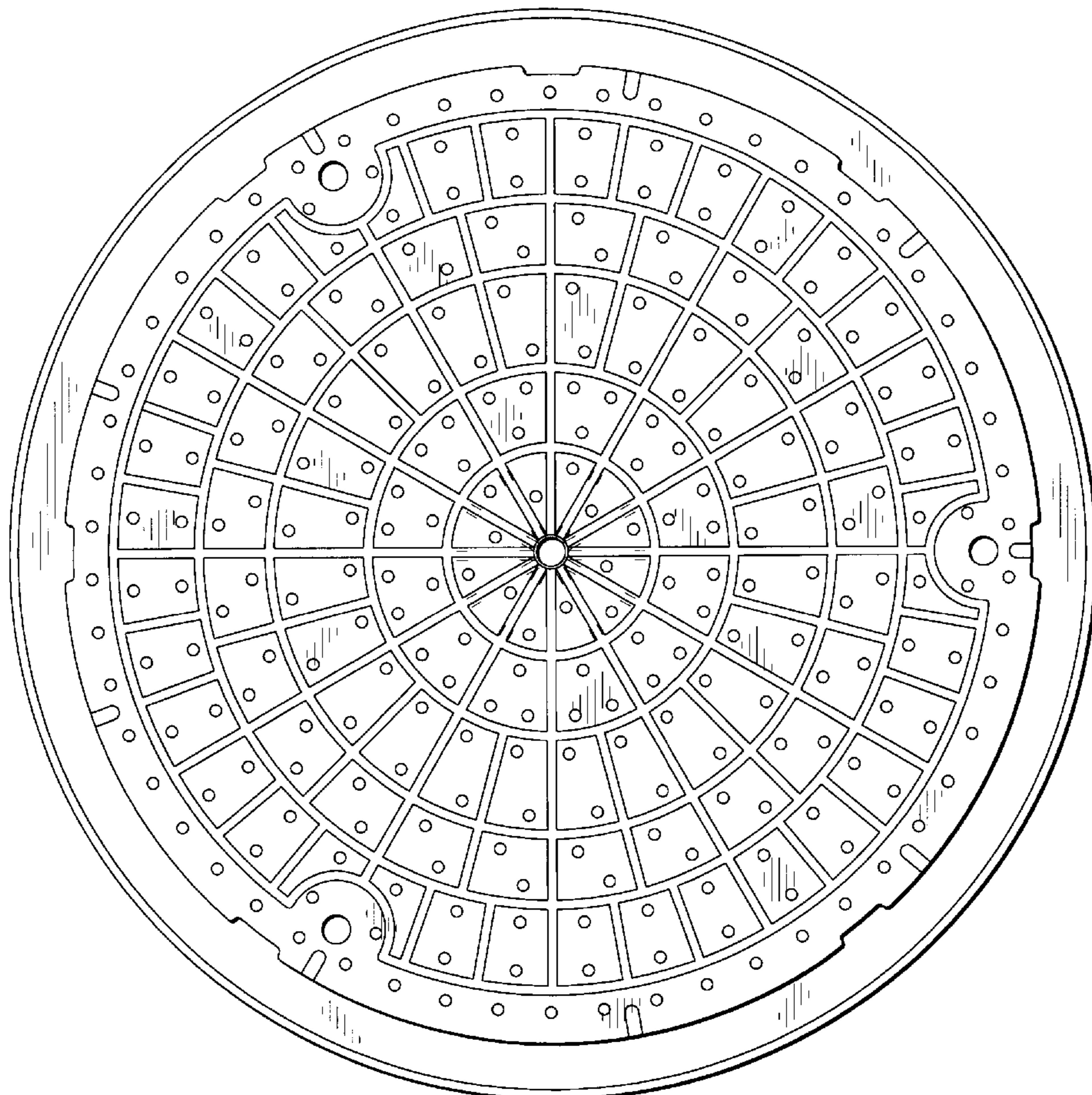


FIG. 1

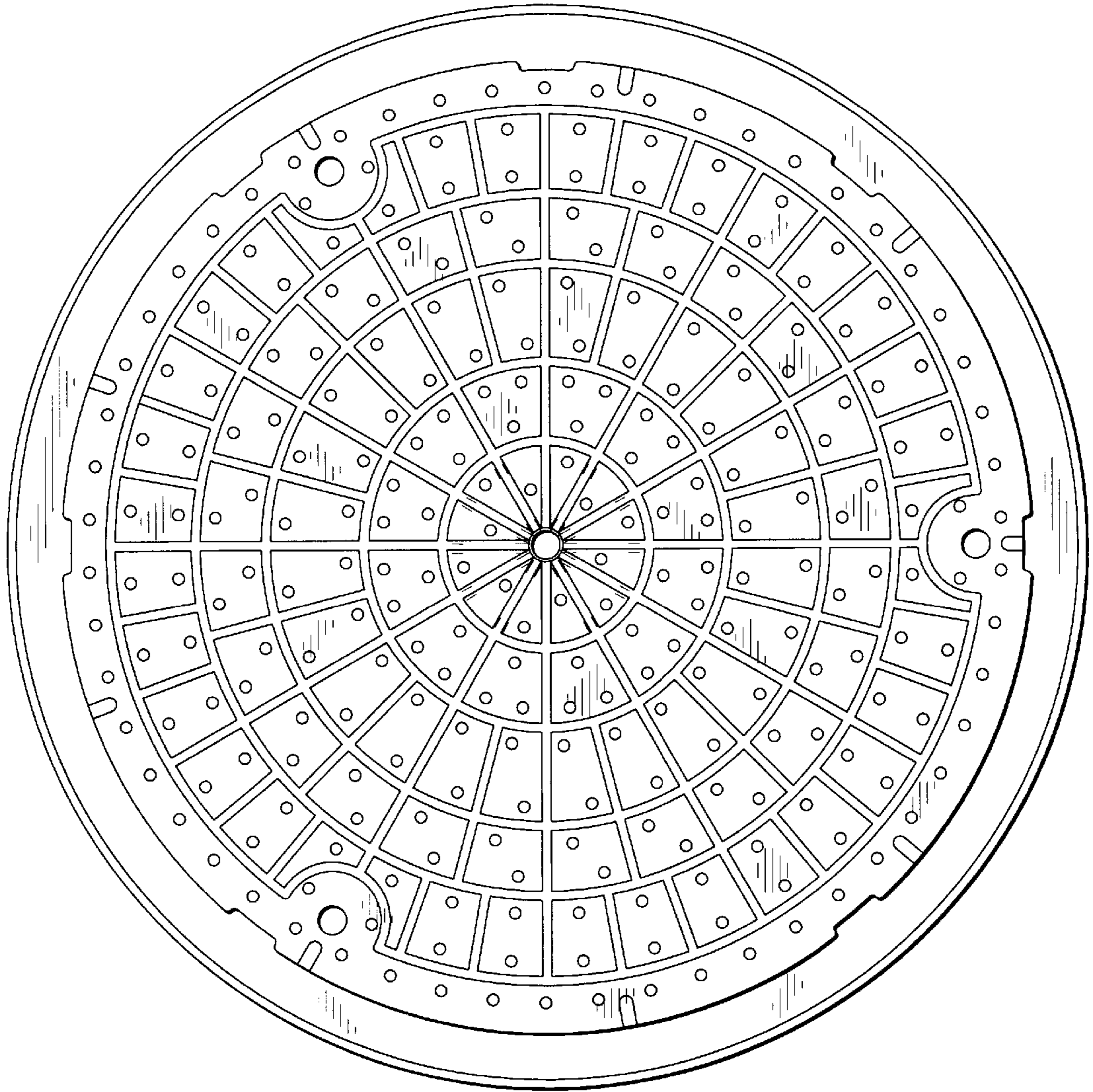


FIG. 2

FIG. 3

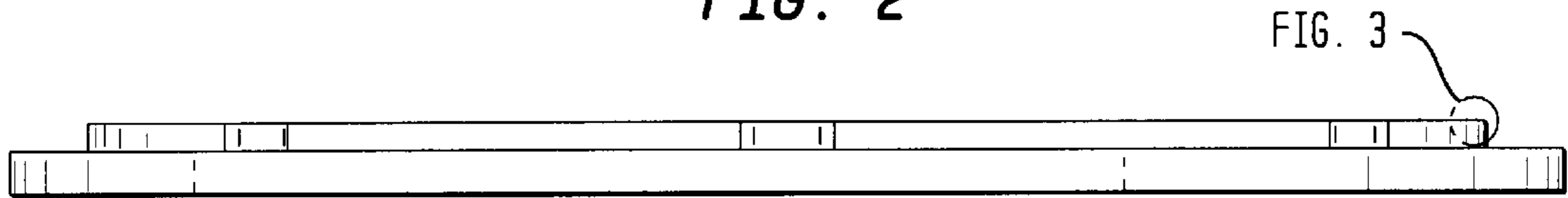


FIG. 3

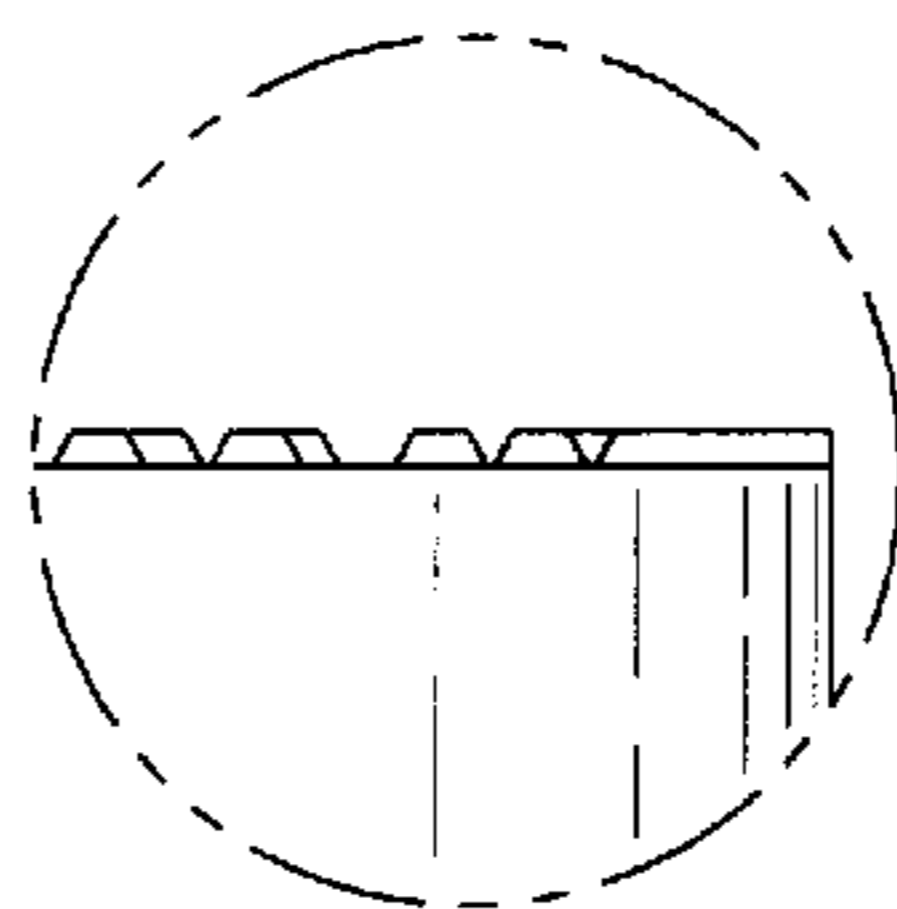


FIG. 4

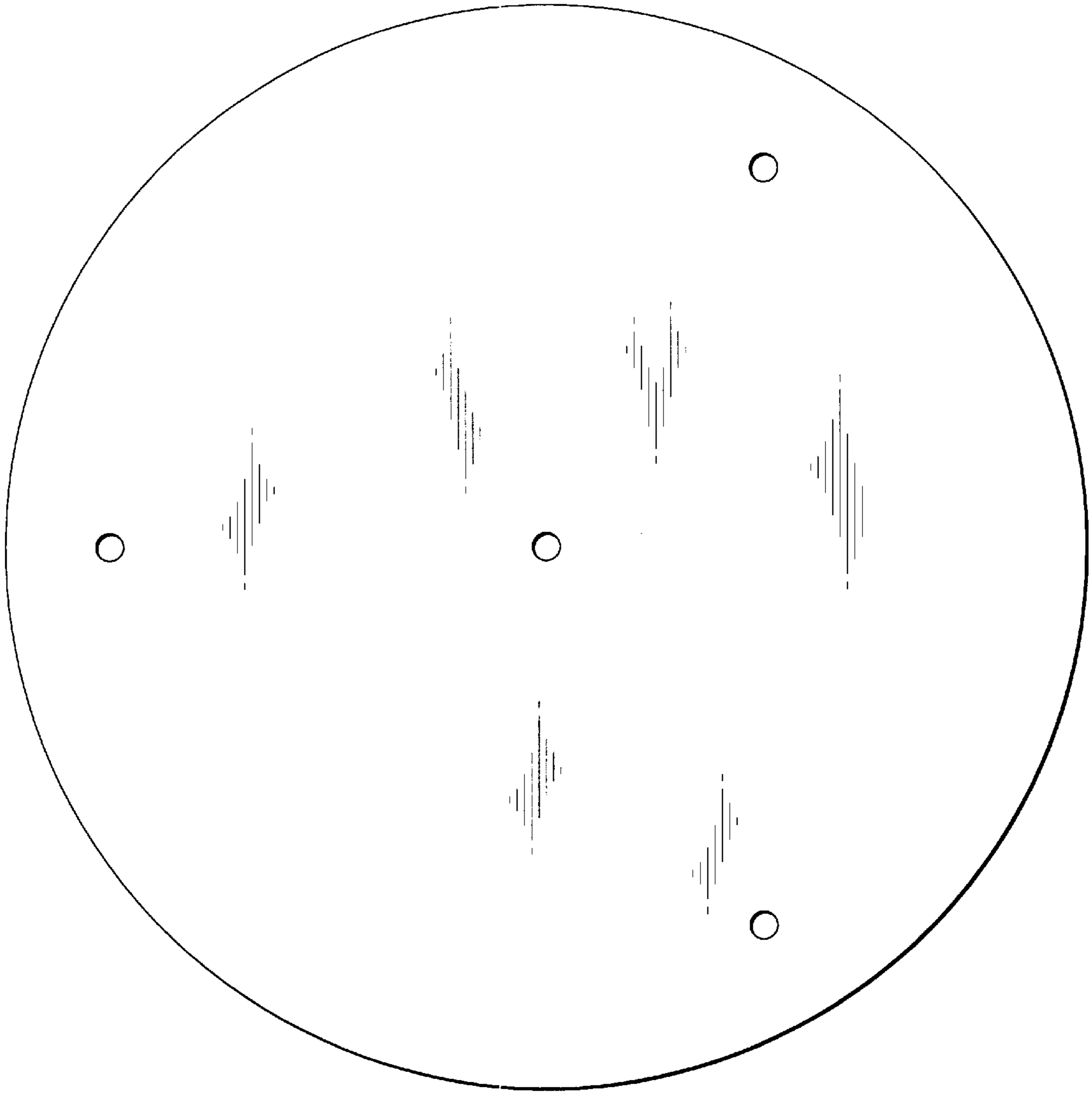


FIG. 5



FIG. 6

